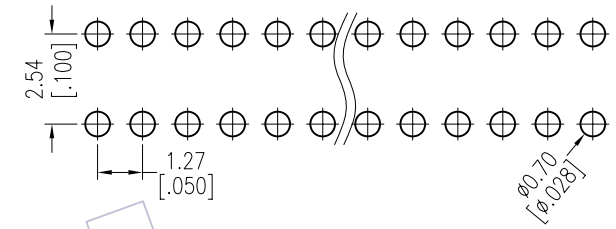
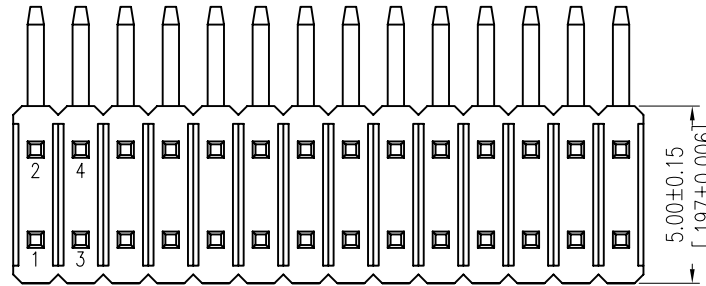


# HSF

NOTES:  
 Rated Current:1.0AMP.  
 Contact Resistance:20mΩ Max.  
 Withstand Voltage:500V AC/DC  
 Insulation Resistance:1000MΩ Min.  
 Operation Temperature:-40°C to +105°C

Contact Material:Brass  
 Contact Plating:Au or Sn Over Ni  
 Insulator Material:PA9T+30%G.F UL94V-0 BK

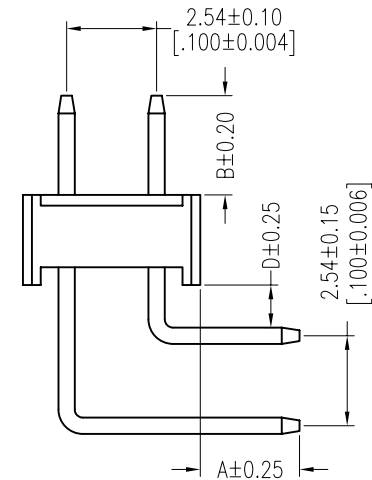
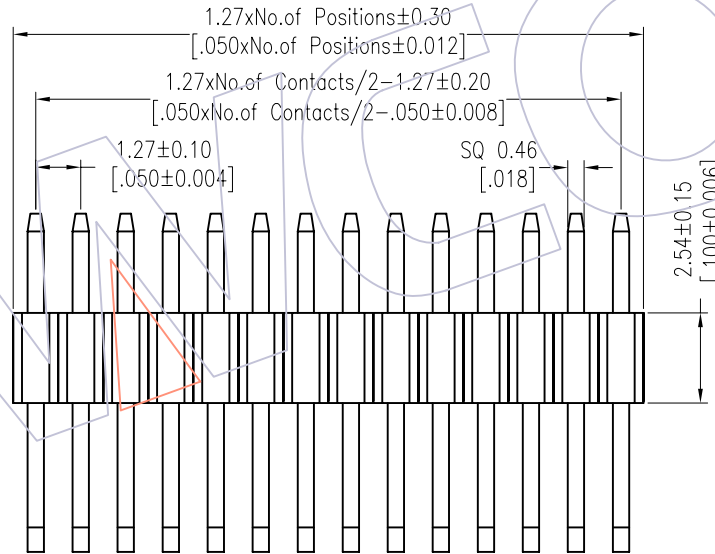
Recommended P.C.B Layout (Top Side)  
 (PCB BOARD TOLERANCE±0.05)



## Ordering Information

1425-12 XX XX R XXX X 1

No.of Pins	Contact Plating	Pin Length(short)	Packing
Per Row:02~50	G0=Gold Flash	L=A+B+D+3.8	A=Tray
	G3=10u"Gold	Standard:106=10.6	T=Tube
	G4=15u"Gold	140=14.0	
	G5=30u"Gold		
	S0=Gold Flash/Tin		
	S3=10u"Gold/Tin		
	S4=15u"Gold/Tin		
	S5=30u"Gold/Tin		



Item	Pin Length	A	D	B	Mating
Standard	10.60	2.80	1.20	2.80	2446
	14.00	3.00	1.20	6.00	2485
Alternate					

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	Fit	PART NO.
				x.x ±0.40	William Chen	2012.04.06	UNIT	mm	1425-12XXXXRXXXXX
				x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE:
				x.xxx ±0.15	APPROVE	DATE	SHEET	1/1	PH1.27*2.54 DUAL ROW 90° CONCAVE BENDING H=2.54
				Angle ± 3'			PROJ.	Customer NO.	
				DIM TOL					